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Shutesh Krishnan
Jatinder Kumar

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2. Name and address of receiving party(ies):

NAME:
SEMICONDUCTOR COMPONENTS INDUSTRIES, L.L.C.
Internal Address: **Law Department – A700**

Street Address: **5005 East McDowell Road**

City: **Phoenix**
State: **Arizona**
Country: **USA** Zip: **85008**

Additional name(s) & address(es) attached? Yes ☐ No ☒

113374 U.S PTO
11/403978
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3. Nature of conveyance/Execution Date(s):

Execution Date(s) December 19, 2005

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
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4. Application number(s) or patent number(s): ☒ This document is being filed together with a new application.

A. Patent Application No.(s):

B. Patent No.(s):

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5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **SEMICONDUCTOR COMPONENTS INDUSTRIES, L.L.C.**
Internal Address: Patent Administration – A700
Street Address: P. O. Box 62890
City, State, Zip: Phoenix, Arizona 85082-2890
Phone Number: 602-244-5358
Fax Number: 602-244-3169/602-244-5601
Email Address: Brad.Botsch@onsemi.com

6. Total number of applications and patents involved: 1

7. Total fee (37 C.F.R. 3.41) $40.00

☐ Enclosed
☒ Authorized to be charged to deposit account

8. Payment Information
Deposit account number: **501086**
Authorized User Name: Kevin B. Jackson

9. Signature.

Kevin B. Jackson
Name of Person Signing

Kevin B. Jackson
Signature

April 12, 2006
Date

Total number of pages including cover sheet, attachments, and document: 2

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FC:8021 40.00 DA

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ONS00647 MALAYSIA

ASSIGNMENT OF ENTIRE INTEREST IN INVENTION BEFORE THE ISSUE OF LETTERS PATENT

Whereas, the undersigned have invented an invention entitled

SEMICONDUCTOR PACKAGE STRUCTURE AND METHOD OF MANUFACTURE

(Attorney Docket No. ONS00647

for which we make application for letters patent in Malaysia; and

Whereas,

SEMICONDUCTOR COMPONENTS INDUSTRIES L.L.C., (SCI), a Limited Liability Company of the State of Delaware, United States of America, having a principal place of business at 5005 E. McDowell Road, Phoenix, Arizona 85008 , United States of America, is desirous acquiring the said invention and the patent thereto:

Now, therefore, for valuable consideration receipt of which is hereby acknowledged, we by these presents, do sell, assign, and transfer unto SEMICONDUCTOR COMPONENTS INDUSTRIES L.L.C. the full and exclusive right in and to the said invention, as described in the specification executed by us preparatory to obtaining letters patent in Malaysia therefor; said invention, application, and letters patent to be held and enjoyed by the said unto SEMICONDUCTOR COMPONENTS INDUSTRIES L.L.C. for its own use and behalf and for its legal representatives, to the full end of the term for which said letters patent may be granted, as fully and entirely as the same would have been held by us had this assignment not been made.

We hereby also sell, assign, and transfer unto SCI, the entire right, title, and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to Malaysia, including all rights under any and all international conventions and treaties in respect of the inventions and the applications for Letters Patent in foreign countries, and we further authorize SCI to apply for Letters Patent in foreign countries directly in its own name, and to claim the priority of the filing date of the application for Letters priority of the filing date of the application for Letters Patent of Malaysia under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Patent Office to issue Letters Patent upon the aforesaid application, division, extension, continuation, or reissue, to SCI, for the sole use and behalf of SCI, its successors, assigns, and legal representatives, to the full end of the term for which the Letters Patent may be granted, the same as they would have been held and enjoyed by us had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to SCI. We agree that, when requested, we will, without charge to SCI, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in SCI, its successors, assigns, and legal representatives or nominees.

We covenant with SCI, its successors, assigns, and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

Executed on the date shown next to my/our name below:

19/12/05

Shutesh Krishnan **Date**

77, TAMAN ENGGANG ,MUAR, JOHOR
MALAYSIA 84000

Witnessed by:
Name: AZHAR ARIPIN
Date: 19/12/2005

19/12/05

Jatinder Kumar **Date**

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Witnessed by:
Name: AZHAR ARIPIN
Date: 19/12/2005